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bility Society Newsletter

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Editors: Gary Kushner and Mark Snyder Vol. 35, No. 2, March 1989 (USPS 460-200)

RS Newsletter Inputs

All RS Newsletter inputs should be sent to one of the associate editors, Gary Kushner, or Mark Snyder, per the following schedule:

For October Newsletter by July 25
For January Newsletter: by Oct. 25
For April Newsletter: by Jan. 25
For July Newsletter: by Apr. 25

Editors: Gary Kushner 499 Bringham St. Marlboro, MA 01752

Mark Snyder
Digital Equipment Corporation
80 Central Street
BxC1-3/B6
Boxboro, MA 01719



Past gifts to Reliability Society.

We will present translations in the dext issue.



Chapter News

Boston

On January 18th our chapter meeting was held at HANSCOM AFB Officers' club in Lexington, MA. Phil Babcock from Charles Stark Draper Labs presented "Next Generation of Reliability Analysis Tools" as the topic of our January Chapter meeting. Phil spoke primarily about the availability of computer programs today, where they are strong, where they are weak, and when ever possible he threw in personal anecdotes. He then moved on to cover briefly where he thought the industry was heading. The meeting was preceded by a social hour and dinner.

The February and March meetings also took place at the Officers' Club. The February talk was entitled "High Density Memory: MIL-2178 vs. Empirical" and the March meeting talk was entitled "Design for Automatic Test." Both topics of obvious interest to our local-area Reliability Engineering professionals was evidenced by the high turnouts. The February talk was given by Vivian Thorsen from Raytheon Corporation and Treasurer of the Boston Section Reliability Chapter. The March Speaker was Jim Deckert.

This month we are putting finishing touches on arrangements for our 27th Annual Spring Seminar entitled "If Quality Is Free, Then Reliability Saves." Over the past several years this all day event has been drawing a large crowd and it looks like this year will be no exception. The seminar will be held at the Sheraton Tara in Framingham, MA on Thursday, April 27th. Some of the speakers presenting papers will be:

Peter Bachant, System Effectiveness Associates, "Solving Reliability Integration as a Part of the CALS Program"

Gene Carrubba, Codex Corporation, "Incorporating Software Reliability Program Requirements into MIL-Standard 785"

Oliver C. Ibe and Anne S. Wein, DEC, "Availability Analysis of systems with Partially observed Failures"

Dr. Michael Elbert, Robert J. Shelton, and Dr. Thomas F. Weyant, DEC, "The New Method for Analyzing Maintainability Without Actual Data"

Daniel J. O'Leary, NESLAB Instruments, Inc., "Inspection Plans and Products Sold under Warranty"

John Peter Rooney, Codex Corporation, MIL-Handbook-217 User Survey"

Dr. Vanzetti, "Laser Infrared Feedback Enhances Solder Joint Reliability"

Those Events round out our activities for this year. We are looking forward to an equally active agenda during the Fall of 1989 and Spring of 1990.

Baltimore Chapter

The Baltimore Chapter is proceeding with a program for the membership. In January, Steven Buswell and Paul Sesto of Westinghouse Electric Corp. spoke on "An Expert System to Facilitate Fault Isolation". Februarys' meeting was entitled "Automated Maintainability & Testability Analysis Supports Concurrent Engineering" by Martin McEnroe & Laura Hildebrand of Westinghouse Electric Corp.

Dallas

Mr. Louis Boudreaux with Texas Instruments is currently working to form a chapter. There are presently 18 members in the area who have signed a petition to form the chapter. His phone number is (214) 575-5687. There have presently been two meetings. The first was for the chapter ADCOM and the second was for the entire chapter with 4]0 plus attending. The next meeting was scheduled for either March or April.

Denver Chapter

A joint ASQC and ieee Reliability Society meeting was held on February 16, 1989. Mr. Ken Shipe of Martin-Marietta Astronautics Product Excellence group was the featured speaker. Mr. Shipe spoke on RAM CAD status and implementation.

The Chapters new officers are: Juan Hernandez as chapter chairman, Bob Jacquess as Vice-Chairman, John Adams as Treasurer, Craig Williams as Secretary, and Ley Andrews as the newsletter chairman.

The chapter has a program of monthly workshops on Software Reliability in addition to the regular meetings.

Los Angeles Chapter

Eight Technical presentations included:

Processor Speeds, Methods for Benchmarking
Designing for Communication Networks of the
Future

Architecture of a Successful Software Environment Designing Reliable User Interfaces

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Fibre Optics—Past, Present, and Future Electronics Parts Purchasing Computer Virus
Desktop Publishing

A mini-course on Artificial Intelligence was held in July. Case Tools seminar was presented in December.

The Chapter purchased a personal computer and has been operating a bulletin board since July. We offer information about the chapter including: monthly technical meetings, the video tape exchange program, listing of officers, job listings, electronic mail and the Open Forum (for an exchange of ideas, comments, etc.)

North Jersey Chapter

The North Jersey Chapter of the IEEE Reliability Society and students and faculty of the New Jersey Institute of Technology (NJIT) jointly sponsored a Symposium on Testability at the Institute on October 18, 1988. A total of 33 guests, including students, attended the symposium, which was followed by a dinner meeting with the speakers in the NJIT Faculty Dining Room.

The program was introduced by Present Chairman Mallik Arjunan and Past Chairman Raymond W. Sears, Jr. Dr. Raj Misra of NJIT ably served as the Sessions Moderator. The Keynote speech for the symposium was delivered by Col. Robert Pinnizotto (USAF) of the Air Force Logistics Command in Dayton, OH. A paper entitled "Reliability Impact of Diagnostics on Fault Tolerance" was presented by Frank Born of Rome Air Development Center, Griffiss AFB, NY. Mary Nolan of Giordano Associates in Pine Brook, NJ, discussed "Army Initiatives in Design Testability" and the preparation of MIL-STD-2165.

The Symposium was well received by the participants and attendees. Reliability Chapter Officers who also assisted were Henry Moss, John Wronka, Shyam Pandey and Sergei Bogaenko. Additionally, Dr. Gary Thomas, Vinu Sundaresen and the students of New Jersey Institute of Technology were instrumental in making the Symposium an informative and successful venture.

Recently our elections were held for the new ADCOM for 1989-1990. Congratulations to Bernhard Bang (president) as he receives the Japanese gift to the local chapter as it is being handed down from three of our past presidents. From left to right, Al Plait (sr. past president), Bernhard Bang (president), Naomi McAfee (sr. past president), and Tom Fagan (jr. past president).

Our new president (Bernhard Bang) on left with Naomi McAfee (past president) and three of Bernhard's committee, Tony Coppola (VP meetings), Al Tamburrino (VP membership), and Paul Gottfried (VP publications).

Bob Jacquess receives a plaque of appreciation for his activities as chairman of the awards committee by outgoing President Tom Fagan.

In this picture, General Goodell receives an award presented by Al Plait from the Reliability chapter.

Philadelphia Chapter

In response to the Society's Newsletter inputs for the Chapter's activities, below are the meetings held for this period. If you require additional information, please feel free to contact me.

September 27, 1988

- Procurement for Reliability of Products Mr. Harvey E. Schock, Jr., Consultant
- Neatness Doesn't Count After All Dr. Hugh Kenner, Johns Hopkins University

October 18, 1988

- Image Processing Techniques for Military Application
 Dr. Frank P. Kuhl, U.S. Army Armament
 - Research and Development Center (ARDC)
- The Executive Master of Science in Engineering (EXMSE) Program at the University of Pennsylvania

Dr. Dwight L. Jaggard

November 15, 1988

• The Aircraft Warning Service, Hawaii (AWS, H) and the Signal Company, Aircraft Warning, Hawaii (SCAWH)

Mr. Stephen L. Johnston, Consultant

March 1989

Reliability Society Officers

PRESIDENT

Bernard Bang Westinghouse Electric Corp. P.O. Box 1521 MS-3G07 Baltimore, MD 21203

JR. PAST PRESIDENT

T. L. Fagan ManTech Int. Corp. 2121 Eisenhower Dr. Alexandria, VA 22314

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Our new president (Bernhard Bang) on left with Naomi McAfee (past president) and three of Bernhard's committee, Tony Coppola (VP meetings), Al Tamburrino (VP membership), and Paul Gottfried (VP publications).



In this picture, General Goodell receives an award presented by Al Plait from the Reliability chapter.



Bob Jacquess receives a plaque of appreciation for his activities as chairman of the awards committee by outgoing President Tom Fagan.

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TRI CITIES

Pete Montague 105 Travelers Way Bristol, TN 37620

WASHINGTON/NORTHERN VIRGINIA

William E. Breslyn 3202-11 University Blvd. West Kensington, MD 20895

New Fellows

Congragulations to the following members of the Reliability Society who were recently elected to the IEEE grade of Fellow.

Prof. Bill D. Carroll Dept. of Comput. Sci. Eng. Univ. of Texas-Arlington P.O. Box 19015 Arlington, TX 76019-0015

For contributions leading to the development of the theory for generalized text functions for combinatorial circuits.

Mr. Thomas L. Fagan, Jr. Man Tech Intl. Corp. 2121 Eisenhower Ave.

For contributions to, and technical leadership in, the field of reliability engineering.

Alexandria, VA 22314

For contributions to the reliability of computer software.

Dr. Amrit L. Goel 5011 Woodside Rd. Favetteville, NY 13066 Fellows Cont.

Dr. Wavne B. Nelson 739 Huntingdon Dr. Schenectady, NY 12309

Prof. Subrahmanyam S. Venkata Dept. of Elect. Engi., FT-10 Univ. of Washington Seattle, WA 98195

For contributions to reliability, accelerated test analysis, and reliability education.

For leadership in electric-power education and research in energy transmission technoloogy.

In the next issue we will present a more personal look at our new fellows.



INTERNATIONAL — RELIABILITY · AVAILABILITY · MAINTAINABILITY Conference for the Electric Power Industry

1989 May 29-June 1

Monterey, California USA

RAM-Solutions for the Competitive 90's

CONFERENCE THEME

The theme emphasizes practical applications of RAM techniques in operating, maintaining, improving, upgrading and extending the life of existing production and delivery systems. It reflects increasing concerns with a future of moderate and uncertain growth, limited resources, complex regulatory requirements, and increasing public involvement and competition as considerations for system operations.

The present situation has also resulted in an increased emphasis and stress on delivery systems. Therefore, in addition to transmission and generation, specific sessions dealing with maintaining and improving distribution systems are planned.

PAPERS

Papers should be consistent with the theme of the Conference. They should discuss practical RAM techniques which have been successfully applied to enhance system performance. In particular, papers dealing with specific case histories are welcome.

ABSTRACTS - [Due 1988 October 1]

A 250-word abstract in English must be forwarded to the Conference Technical Program Chairman, as listed below.

Abstracts should be structured with the following three sections: problem or questions addressed; work performed; and results and/or conclusions reached. Abstracts should be typed on a single sheet and should include the title; names and affiliations of all authors; address and telephone number of presenting author; and a list of 5 key words. A short (150 word) professional biography for each of the authors should accompany the abstract, and the presenter should be identified.

The selection results will be transmitted to the authors by 1988 December 1. Completed papers of 4000 words or less will be required by 1989 February 15.

EXHIBITS

Arrangements are being made for an exhibition during the conference in the conference hotel. Industrial, Technological and Educational exhibits will be welcome. Exhibitors are encouraged to make arrangements as soon as possible.

1989 INTERNATIONAL RELIABILITY PHYSICS SYMPOSIUM

April 10-13, 1989 • Hyatt Regency • Phoenix, Arizona

The 27th Annual Symposium, co-sponsored by the IEEE Reliability Society and the Electron Devices Society, has as its major theme, building-in and validating for present and developing VLSI and hybrid technologies.

Packaging (bonding, die and substrate attachment, coating, encapsulation, sealing, glass-metal seals)

PAPERS on the following subjects.

- VLSI Package Design and Construction for High Reliability
- Building-in Reliability: Design and Process Control for Si and GaAs
 Designing circuits, multi-chip assemblies, and subsystems
 Materials selection and control; epoxy adhesives
 Process design and control; computer-integrated manufacturing
- Analysis for Reliability
 Failure analysis techniques (new, advanced, simplified)

Failure mechanisms and models, for example:
electrostatic discharge
hot carrier effect
electromigration
oxide breakdown

contact degradation and corrosion surface mount packages mechanical and thermal stress

Methodologies

wafer-level controls accelerated stress test combinations statistical process control screening
field failure mechanisms
burn in effectiveness and strategy
analytical instruments and techniques

For general conference information contact:

Bruce Euzent General Chairman, 1989 IRPS Intel Corp. 2250 Mission College Blvd. SC9-06 P.O. Box 58125 Santa Clara, CA 95052-8125 Tel. 408-765-9400 Asia
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Balanstr, 73
D-8000 Munich 80
Federal Republic of Germany
Tel. 089 4144-2825

SYMPOSIUM FEATURES

- Proceedings at Symposium
- Tutorials and Workshops
- Hands-on, one-on-one, analytical equipment demonstrations.
- Awards Presentations
- Authors corners and attendee lounge for discussions

Conference Calendar

DATE	CONFERENCE	PLACE	CONTACT
1989			
Apr. 11-13	1989 International Reliability Physics Symposium	Phoenix, AZ	Alfred Tamburrino Member, Board of Director RADC/RBRP Griffiss AFB, NY 13441 (315) 330-2813
Apr. 12-13	Product Assurance Forum '89	Dover, NJ	Sid Markowitz Registration Chairman U.S. Army Picatinny Arsenal Building 62 Dover, NJ 07806-5000 (201) 724-2378
Apr. 27	27th Annual Spring Reliability Seminar	Framingham, MA	John Morgan Digital Equipment Corp. ML1-2/U2 146 Main St. Maynard, MA 01754
May 29 – Jun. 1	1989 16th International Reliability, Availability Maintainability Conference for the Electric Power Industry	Monterey, CA	Robert W. Filipovits General Vice Chairman Pennsylvania Power & Light P.O. Box 3328 Wescosville, PA 18106 (215) 398-5158
June 14-16	Reliability '89	Brighton, England	R. Campbell Reliability '89 National Centre of Systems Reliability UKAEA, Wigshaw Lane Culcheth, Warrington WA3 4NE England 0925-31244 X4243 Telex: 629301 Atomry G.
Aug. 21-25	Semiconductor Packaging, Testing and Reliability	Davos, Switzerland	Dr. Birgit E. Jacobson CEI-Europe P.O. Box 910 612 01 Finspang Tel: 0122-17 570 Telefax: 0122-143 47
Sept. 25-28	Autotestcon	Philadelphia, PA	Fred Liguori 38 Clubhouse Road Browns Mills, NJ 08015
Sept. 26-29	V International Conference on Performance Evaluation, Reliability and Exploitation of Computer Systems, Relcomex '89	Ksiaz Castle, Poland	Relomex '89 Institute of Engineering Cybernetics Wroclaw Technical Univ. Janiszewskiego Str. 11-17 50-372 Wroclaw, Poland Prof. Wojciech Zamojski (Tel. 21-26-77) Dr. Ireneusz Jozwiak (Tel. 20-28-23) Telex 0712254 PWR PL 0712559 PWR PL

March 1989

Oct. 9-11	Reliability, Achievement—The Commercial Incentive	Stavanger, Norway	Terje Aven Statoil Box 300 4001 Stavanger, Norway
			+ 47-4-80 80 80
			Telex: 73 600 Stast N
			Telefax: +47-4-80-98-89
1990			
Jan. 30 - Feb. 1	1990 Annual Reliability and Maintainability Symposium	Los Angeles, CA	V. R. Monshaw RCA Corporation
			Astro-Electronics P.O. Box 800 MS 55
			Princeton, NJ 08540 (609) 426-2182
Mar. 26-29	1990 International Reliability	New Orleans, LA	Alfred Tamburrion
	Physics Symposium		Member, Board of Director RADC/RBRP
			Griffiss AFB, NY 13441 (315) 330-2813
1991			COLUMN TO THE PARTY OF THE PART
Jan. 29-31	Annual Reliability and	Orlando, FL	V. R. Monshaw
	Maintainability Symposium	A TO SERVICE OF THE S	RCA, Astro-Electronics P.O. Box 800, MS 55
			Princeton, NJ 08540 (609) 426-2182
Apr. 8-11	1991 International Reliability Physics Symposium	Las Vegas, NV	Alfred Tamburrino Member, Board of Director
	The state of the s		RADC/RBRP
		malandi thorografi	Griffiss AFB, NY 13441
			(315) 330-2813
Sept. 24-26	1991 IEEE Autotestcon	Anaheim, CA	Robert C. Rassa Mantech Advance Systems International
			150 S. Los Robles Ave Suite 350 Pasadena, CA 91101
1992			
Jan. 27-29	Annual Reliability and Maintainability Symposium	Las Vegas, NV	V. R. Monshaw RCA, Astro-Electronics
	Manital and Symposium		P.O. Box 800, MS 55
			Princeton, NJ 08540 (609) 426-2182
1993			
			V. D. Mansham
Jan. 26-28	Annual Reliability and Maintainability Symposium	Atlanta, GA	V. R. Monshaw RCA, Astro-Electronics
			P.O. Box 800, MS 55 Princeton, NJ 08540
			(609) 426-2182

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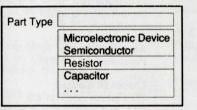
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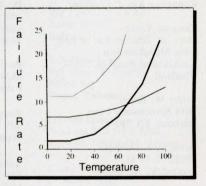
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PII	:	1.00000
Plq	:	2.00000
PIt	:	0.10131
PIV	:	1.00000
C1	:	0.01000
C2	:	0.00366
Failure Rate		0.067845

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Innovative Software Designs, Inc.

One Kimball Ridge Court Baltimore, MD 21228 (301) 747-8543

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New Members

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Tech Ops Committee Reports

Systems Screening Committee: William E. Wallace, Jr. Chairman

Bill's report is attached in which he has reviewed the draft of NAVMAT P-9492. I commend reading his report but the gist is his disappointment in the lack of specific recommendations on how to carry out such a program (test levels, etc.), and some technical disagreements. Bill has done a lot of work and I thank him. Inputs from others are still encouraged.

Nuclear Reliability Committee: David J. Campbell, Chairman

At the last ADCOM meeting, Dave presented a desire to create a probability Risk Assesment (PRA) procedures guide. He has contacted his peers and finds not much interest. Therefore, the plan will be set aside. In the meantime, the NRC has issued a general letter requiring all nuclear facilities to produce a PRA. Some guidelines are included. Dave feels that these are inadequate and is now considering a symposium on PRA procedures.

Human Performance Reliability Committee: Ken LaSala, Chairman

Working with others, he anticipates that a letter of inquiry will be released in February, asking industry and government, what work is being done to estimate Human Performance Reliability, what models and techniques are

Mechanical Reliability Committee: Richard Doyle, Chairman

Dick is now gathering committee members for his effort to determine the Mechanical Reliability of Electrical Systems. His roster of members is attached. I am enthusiastic about this effort since I believe it is an arena that needs attention.

Energy Systems Reliability Committee: Dr. Chanan Singh,

Dr. Chanan is in contact with Dr. Thad Regulinski regarding a special issue on power system reliability.

1988 Software Reliability Technical Committee Report

Irv Doshay, Chairman

coming of age to join the actual practice of Hardware received the blessing of "all the gods" and in the process Reliability in the form of Combined Hardware/Software of the Institute's preparation for release in March (this year). Reliability Analysis and Control Techniques. RADC is cur- However, draft copies are still available from the Institute. rently funding a project which has as its objective the (345 E. 47th St., New York, NY 10017) preparation of a manual of practical techniques that would Preliminary findings are that it is well supported by detailly to be the simple examples that abound in every chapter. seriousness of software reliability).

It is beginning to appear that Software Reliability is finally The IEEE Standard, P982 on Software Reliability has finally

Much activity is underway by the EIA, and is covered by cover the entire realm of necessary tasks. A book by Musa, Myron Lipow, who is our key advocate working with the Iannino, and Okumoto was published by McGraw-Hill on EIA Government Committees (G33, 34, and 41). His report Software Reliability Measurement, Prediction and Applica- is attached below. Of special note is the expectancy of a tion and it is currently being reviewed by the undersigned. revised MIL-STD-785 to include Software Reliability. It is also noted that MIL-STD-882B has been updated with a ed mathematical formulii, along with support data and or Notice 1, that included extensive additions covering Softderivation. However, the most useful facet of the text is like- ware Safety (which are basically outgrowths of the

Report on Software Reliability Activity, 1988

January 1988

meeting, January 19-20, in Washington, DC, the continua- STD-785B to be proposed were agreed upon. Highlights of tion of MIL-STD-785 B upgrade activity was planned. This the panel discussions were: was a joint meeting of the G-34 Software Reliability Subcommittee of G-34 and the chairman (E. Godin) of the G-41 Reliability Committee. This meeting followed a detailed review of MIL-STD-785B in November, 1987 at the Savannah EIA G-33/G-34 Workshop, whose report was prepared and issued in early 1988.

June 1988

At the June 21, 22 meeting of the G-34 Committee in Washington, the Software Reliability Subcommittee met, along with the chairman and members of G-41 to discuss unresolved issues on MIL-STD-785B. On 23 June, assignments to draft the changes to the MIL-STD-785B tasks were accepted by attendees and their associates.

September 1988

At the annual workshop of the G-33/G34 Committees in Minneapolis, September 26-29, the edited draft changes were brought to the meeting of Sub-Panel 2A (of the Software Quality Panel), which consisted primarily of G-34 and

At the EIA G-34 (Computer Resources Committee) G-41 members, and final versions of the changes to MIL-

- 1) Review of new material on software sneak analysis, submitted by Charles Carpenter of Mitre Corporation. 2) New material was incorporated into the Parts Program (Task 207) which involves reusable software components, a keystone of the DoD STARS Program, and one of the major efforts of the Software Productivity Consortium.
- 3) A resolution for further cooperation between the G-41 and G-34 committees to follow up the proposed changes to the MIL-STD-785B to be submitted through the EIA to the Office of Primary Responsibility of the MIL-STD, as well as to work on software reliability technology applications.

The final report of SubPanel 2A was submitted to the Workshop Chairman in December 1988, and contains all the details of the proposed changes to MIL-STD-785B.

> Myron Lipow 9 January, 1989

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Maintainability Committee Report

The maintainability committee is a part of the technical operating segment of the Reliability Society of the IEEE. It is responsible for matters associated with the disciplines of maintainability and testability engineering as they relate to electrical and mechanical design. The purpose of the committee is to provide a focal point for the dissemination of discipline related activities. It shall function to provide traditional maintainability/testability coverage and keep the membership of the society abreast of new initiatives and advances in the state of the art. Initiatives such as Modular Avionics Systems Architecture (MASA), R&M 2000, Avionics Integrity Program (AVIP), etc. will be included in committee operations to the extent that is required to provide adequate coverage. The recent emphasis on Computer Aided Acquisition and Logistic Support (CALS) and "Concurrent" engineering will be tracked to assure that coordination and linkages to the maintainability area are actively reviewed and, as applicable, presented to the society membership.

There are several objectives that will be pursued for 1989 that hopefully will broaden and strengthen the coverage of maintainability within the society. Initially it will be of utmost importance to recruit interested IEEE members to

assist and participate in committee functions. This participation will be managed to minimize the time burden on committee members and supporters. It is desired that a cadre of professionals that work these specialty areas be assembled to form a core group. This group will be responsible for the promotion of the committees objectives and the expansion of maintainability activities within the society. In addition, it is expected that interfaced with other professional/industrial organizations will be established to provide for the exchange of information and activities pertinent to this committee. Another action that will facilitate meeting these objectives will be the establishment of a unique newsletter column. The planning for this has begun and will hopefully satisfy the appetite of those looking for information about this field. Those IEEE members that are interested in this committee or who would like to contribute information are asked to contact the chairman.

> Mr. J. A. Gruessing, Chairman Westinghouse Electric P.O. Box 746, MS 5380 Baltimore, MD 21203 (301) 765-7070

Maintainability/Testability Affairs

IDSS CAD Tool Development

18

A recent article in the ATE Newsletter (October 88') provided insight into the Navy's IDSS Program. This program will provide a new approach to diagnostic development placprocess. The program known as the Integrated Diagnostic Support System in being developed to utilize two CAD tools to support both hardware and software design while additional interfacing tools complement associate maintenance function development. Two of the tools will be available about mid-year for "Beta" site testing with distribution to interested contracting design facilities. The software is written in the ADA programming language and can be hosted on workstations using UNIX or VMS operating systems.

These tools will be made available at no cost to contractor representatives. The CAD programs that will be available are the Weapon System Testability Analysis (WSTA) and ing most emphasis on the application of CAD tools to the the Adaptive Diagnostic Authoring (ADA) tools. The WSTA will be capable of generating optimum test strategy in terms of test time and cost. It will use digital and analog topology coupled with logistics support analysis data as tool inputs to produce maintainability and testability figures of merit. The ADA tool will develop the diagnostic software program through the validation of WSTA test strategy, IDSS data base information, and integration of production rules. The article indicated that additional information could be obtained from Jim Cigler (202) 692-0170.

Transactions Changes

The recent changes in the structure of the Transactions' editorial functions have been followed by an increase in the number of Associate Editors. This increase allows the Associate Editors to focus on papers closely related to their specialty areas. It also requires a new mechanism for distributing manuscripts among the Associate Editors. The implementing procedures are:

1) ALL manuscripts are to be sent to the Managing Editor Dr. Ralph A. Evans IEEE Transactions on Reliability 804 Vickers Avenue Durham, NC 27701 USA

in accordance with the instructions for Submission of Manuscripts in "Information for Readers & Authors" at the rear of each issue of the Transactions. (This does not apply to manuscripts for Special Issues.)

- 2. The Managing Editor will acknowledge the submittal, send a special yellow IEEE Copyright Form to the author, and forward the manuscript to the editor (as Associate Editor or the Editor) who will handle the refereeing/acceptance process in its entirety.
- 3. All further correspondence about the manuscript will be with that editor, until (and if) the manuscript is to be published. The author will receive appropriate instructions at that time.
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- INCORPORATING SOFTWARE RELIABILITY PROGRAM REQUIREMENTS INTO MIL-STD-785.
 Gene Carrubba, Codex Corporation
- AVAILABILITY ANALYSIS OF SYSTEMS WITH PARTIALLY OBSERVABLE FAILURES.
 Oliver C. Ibe and Anne S. Wein, Digitial Equipment Corporation
- MIL-HDBK-217 USER SURVEY.
 John Peter Rooney, Codex, Corporation
- THE NEW METHOD FOR ANALYZING MAINTAINABILITY WITHOUT ACTUAL DATA.
 Dr. Michael Elbert, Robert J. Shelton, and Dr. Thomas F. Weyant, Digital Equipment Corporation
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